



Datasheet

Part No.: Description:

Features:

### DSGP.1575.12.4.A.02

GPS L1 / GALILEO E1 1575MHz Ceramic SMD Patch Antenna

2.73 dBi Peak Gain for GPS/GALILEO Band SMD Mount Ceramic Patch Antenna Dimension: 15 x 15 x 2mm Automotive IATF16949 Production and Quality Approved RoHS Compliant





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### 1. Introduction



The DSGP.1575.12.4.A.02 is a ceramic GPS L1 / GALILEO E1 passive patch antenna. 12mm square and with a height of just 4mm, this antenna is perfect for applications in compact telematics devices, vehicle tracking/fleet management systems, wearables and navigation devices.

The antenna has been tuned on a 50\*50mm ground plane, working at 1575.42MHz with a 2.73dBi gain. The ceramic patch is mounted via SMT process, suitable for high-volume low-cost assembly.

The antenna is manufactured and tested in a TS16949 first tier automotive approved facility.

Small antennas should ideally be custom tuned for the device environment, Taoglas offers this service subject to NRE and MOQ. For more details please contact your regional Taoglas sales office.



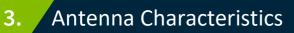
# Specifications

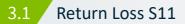
2.

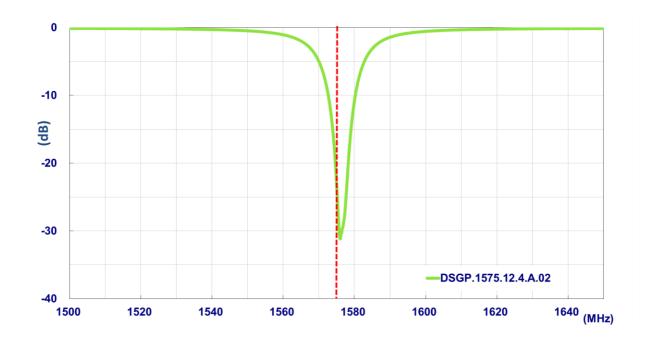
	ELECTRICAL	
Application Bands	GPS L1/GALILEO E1	
Frequency	1575.42 ±1.023 MHz	
Return Loss	<-10	
Efficiency	62.36%	
Peak Gain	2.73 dBi	
Polarization	RHCP	
Impedance	50 Ω	
	MECHANICAL	
Dimensions	15 x 15 x 2 mm	
Material	Ceramic	
Weight	3.3g	
	ENVIRONMENTAL	
Operation Temperature	-40°C to 85°C	
Storage Temperature	-40°C to 105°C	
Humidity	Non-condensing 65°C 95% RH	
Moisture Sensitivity Level (MSL)	3 (168 Hours)	

st Antenna properties were measured with the antenna mounted on 50st50mm Ground Plane

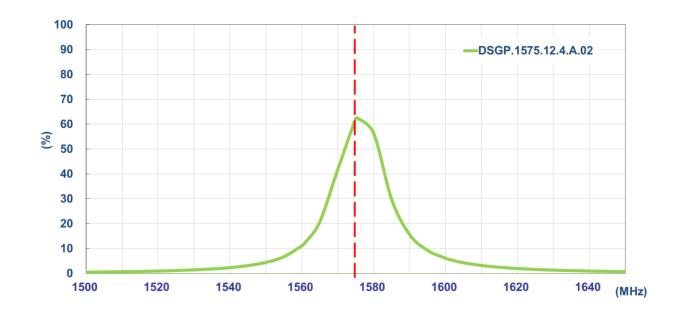




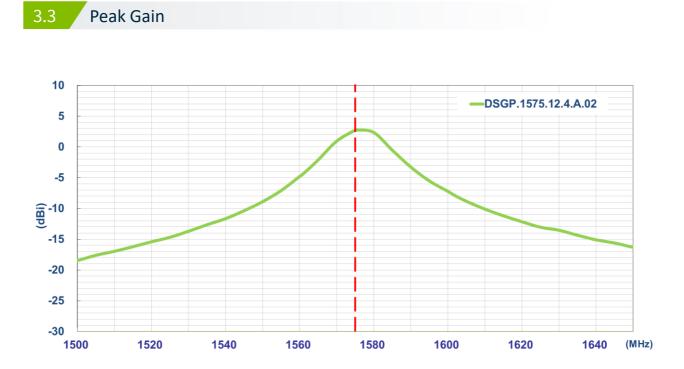




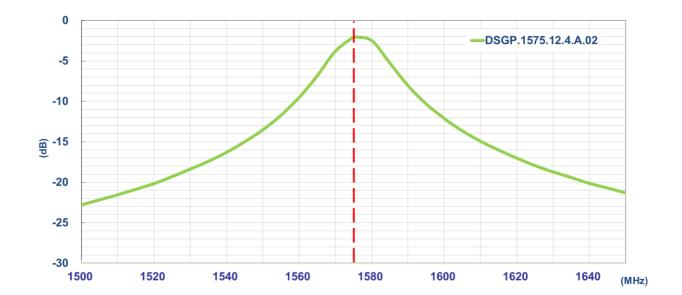
#### Efficiency 3.2









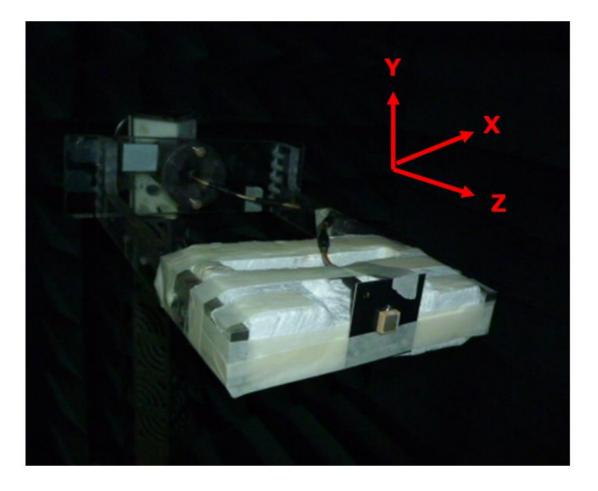




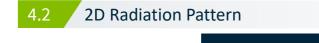
# Radiation Patterns



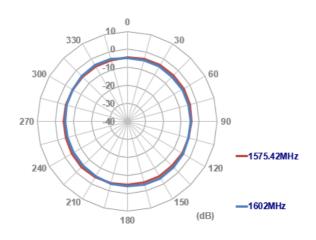
4.

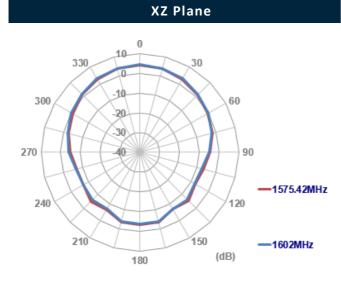




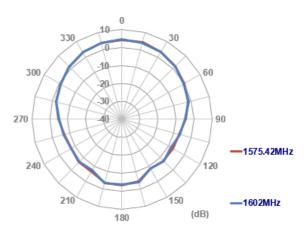


XY Plane



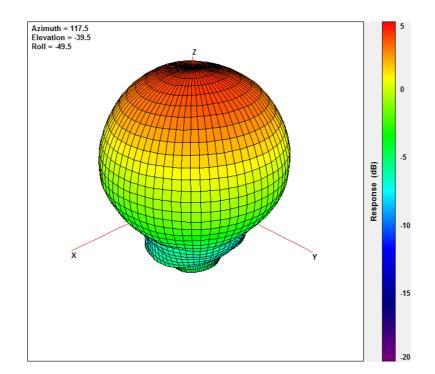




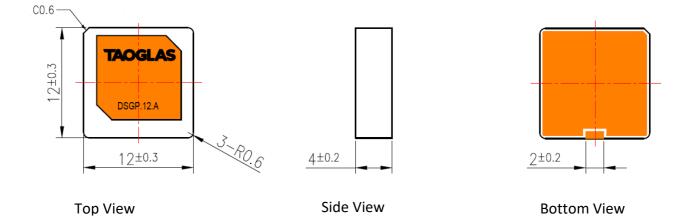




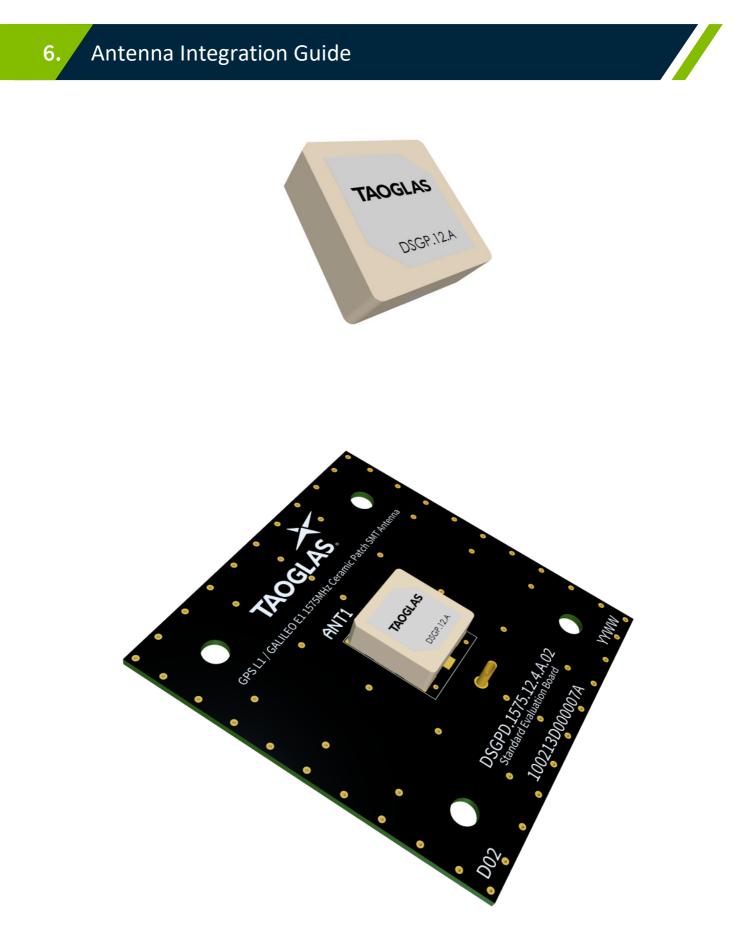
### 4.3 3D Radiation Patter









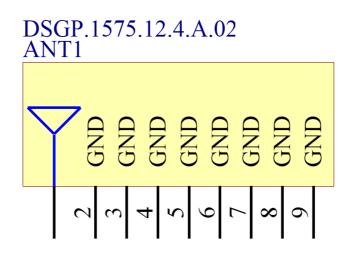




### 6.1 Schematic Symbol and Pin Definition

The circuit symbol for the antenna is shown below. The antenna has 9 pins as indicated below.

Pin	Description	
1	RF Feed	
2, 3, 4, 5, 6, 7, 8, 9	Ground	





#### 6.2 Antenna Integration

The antenna should be placed at the center of the ground plane with a length and width of 50mm. Maintaining a square symmetric ground plane shape and symmetric environment around the antenna is critical to maintaining the excellent axial ratio and phase center performance shown in this datasheet.



Top Side w/ Solder Mask



Top Side w/o Solder Mask

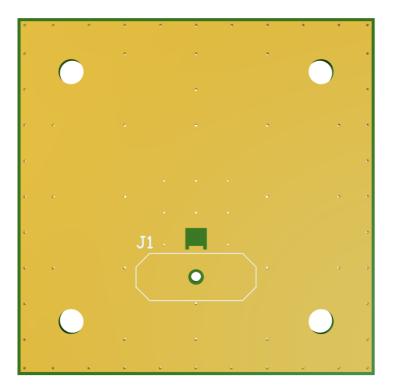


### 6.3 PCB Layout

The footprint and clearance on the PCB must comply with the antenna specification. The PCB layout shown in the diagram below demonstrates the antenna footprint.



Topside

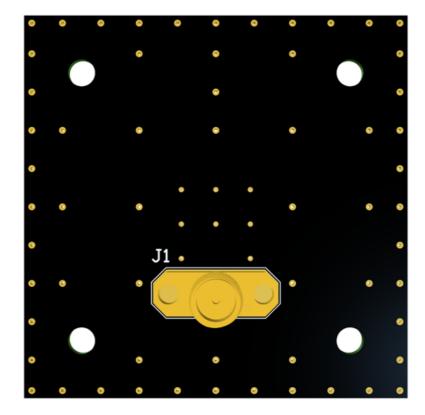


Bottom Side





Topside

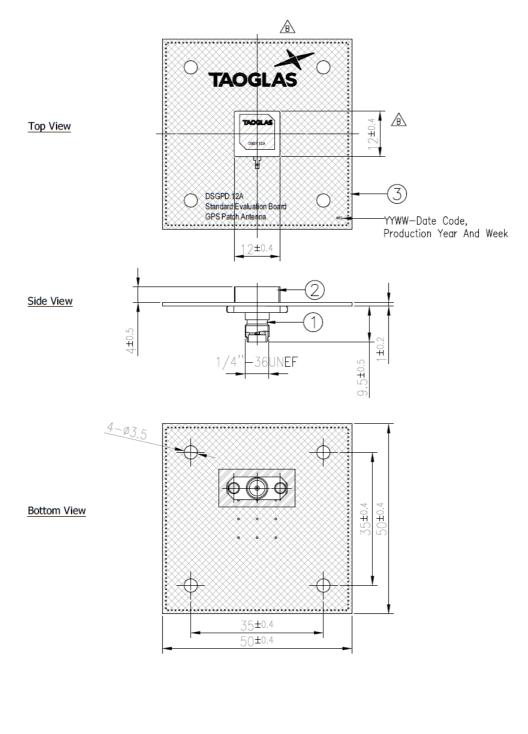


**Bottom Side** 

6.4



## Evaluation Board Mechanical Drawing



Notes

1.	Silver area	V///
2.	Solder mas	( 🖾

1.	Silver area	/////
2.	Solder mask	
3.	Solder Area	

	Name	P/N	Material	Finish	QTY
1	PCB SMA(F) ST	200411I000007A	Brass	Au Plated	1
2	DSGP.1575.12.4.A.02 Antenna	001514L040007A	Ceramic	Clear	1
3	PCB (50x50x1mm)	100213D000007A	FR4 1.0t	Black	1

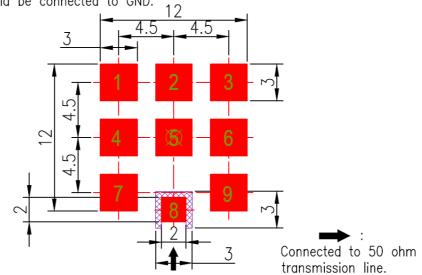
7.



### 8. PCB Footprint Recommendation

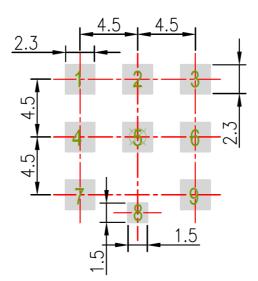


Pads 1, 2, 3, 4, 5, 6, 7 and 9 are the same size. They should be connected to GND.



#### 8.2 Paste Area (Unit: mm)

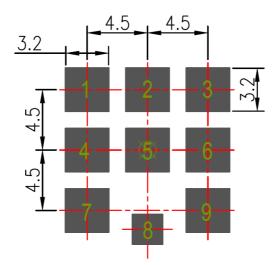
Pads 1, 2, 3, 4, 5, 6, 7 and 9 are the same size.



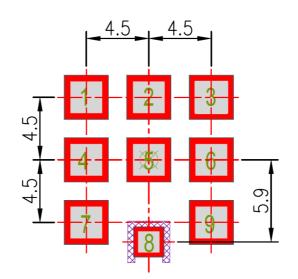


#### 8.3 Top Solder Mask (Unit: mm)

Pads 1, 2, 3, 4, 5, 6, 7 and 9 are the same size, This drawing is a negative of solder mask. Black regions are anti-mask.



### 8.4 Composite Diagram (Unit: mm)

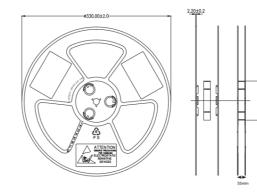


#### NOTE:

- 1. Ag Plated area
- 2. Solder Mask area
- Copper area
  Paste area
- 5. Copper Keepout Area
- 6. Copper keepout should extend through all PCB layers.
- 7. Any vias in pads should be either filled or tented to prevent solder from wicking away from the pad during reflow.
- 8. The dimension tolerances should follow standard PCB manufacturing guidelines.

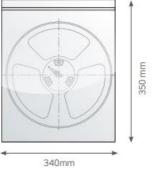


## 9. Packaging

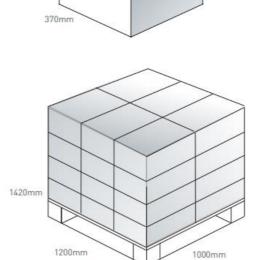


500 pc DSGP.1575.12.4.A.02 per reel Dimensions - Ø330\*55mm Weight - 2300Kg









305mm

Pallet Dimensions 1200\*1000\*1420mm 24 Cartons per Pallet 6 Cartons per layer 4 Layers



360mm



Changelog for the d	atasheet
SPE-17-8-028-D	SGP.1575.12.4.A.02
Revision: B (Current	Version)
Date:	2023-03-23
Changes:	Antenna Integration Guide Added
Changes Made by:	Cesar Sousa

#### **Previous Revisions**

Revision: A (Original First Release)	
Date:	2018-05-17
Notes:	
Author:	Technical Writer
Author:	Technical Writer





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